

Thursday, September 8

Session 1: Plenary Session (Seiun)

Chairpersons: Y. Kamakura, *Osaka Univ., Japan*
N. Goldsman, *Univ. Maryland, USA*

9:05

Opening and Welcome Remarks

K. Matsuzawa
Toshiba, Japan

9:15

1-1 TCAD Challenges and some Fraunhofer Solutions

J. Lorenz
Fraunhofer IISB, Germany

10:00

1-2 Critical Analysis of 14nm Device Options

P. Oldiges, R. Muralidhar, P. Kulkarni, C-H. Lin, K. Xiu, D. Guo, M. Bajaj and
N. Sathaye
IBM Corp., USA

10:45

1-3 First-principles study of Si CMOS materials and nanostructures

K.-J. Chang¹, H.-K. Noh¹, E.-A. Choi² and B. Ryu³
¹KAIST, Korea, ²Samsung Electronics Co., Ltd., Korea and ³Samsung Advanced Institute of
Technology, Korea

11:30 **Lunch**

Session 2: Reliability I (Ginga)

Chairpersons: Y. Oda, *Panasonic, Japan*
T.-M. Shen, *TSMC, Taiwan*

13:00

2-1 Quantum-Mechanical Modeling of NBTI in High-k SiGe MOSFETs

Ph. Hehenberger¹, W. Goes¹, O. Baumgartner¹, J. Franco², B. Kaczer² and T. Grasser¹
¹TU Wien, Austria and ²IMEC, Belgium

13:20

2-2 Multi Scale Modeling of Multi Phonon Hole Capture in the Context of NBTI

F. Schanovsky, O. Baumgartner and T. Grasser

TU Wien, Austria

13:40

2-3 Modeling Statistical Distribution of Random Telegraph Noise Magnitude

K. Sonoda, M. Tanizawa, K. Ishikawa and Y. Inoue

Renesas Electronics Corp., Japan

14:00

2-4 A Compact Model for Early Electromigration Lifetime Estimation

R. L. de Orio, H. Ceric and S. Selberherr

TU Wien, Austria

Session 3: Nanowire (Izumi)

Chairpersons: N. Mori, *Osaka Univ., Japan*

A. Akturk, *Univ. Maryland, USA*

13:00

3-1 Effects of Atomic Disorder on Carrier Transport in Si Nanowire Transistors

H. Minari^{1,3}, T. Zushi², T. Watanabe^{2,3}, Y. Kamakura^{1,3} and N. Mori^{1,3}

¹*Osaka Univ., Japan*, ²*Waseda Univ., Japan* and ³*CREST, Japan*

13:20

3-2 Strong Anisotropy and Diameter Effects on the Low-Field Mobility of Silicon Nanowires

N. Neophytou and H. Kosina

TU Wien, Austria

13:40

3-3 Simulation of Channel Electron Mobility Due to Scattering with Interfacial Phonon-Plasmon Modes in Silicon Nanowire under the Presence of High-k Oxide and Metal Gate

K. Xiu

IBM SRDC, USA

14:00

3-4 Fully Analytic Compact Model of Ballistic Gate-All-Around MOSFET with Rectangular Cross Section

T. Numata^{1,4}, S. Uno^{2,4}, Y. Kamakura^{3,4}, N. Mori^{3,4} and K. Nakazato¹

¹Nagoya Univ., Japan, ²Ritsumeikan Univ., Japan, ³Osaka Univ., Japan and ⁴CREST, Japan

14:20

3-5 Analytical model of drain current in nanowire MOSFETs including quantum confinement, band structure effects and quasi-ballistic transport: device to circuit performances analysis

J. Dura^{1,2}, S. Martinie², D. Munteanu², F. Triozon¹, S. Barraud¹, Y.M. Niquet³ and J.L. Autran²

¹CEA-LETI MINATEC, France, ²UMR CNRS, France and ³INAC, France

14:40

3-6 Electron-phonon scattering in Si and Ge: from bulk to nanodevices

D. Rideau¹, W. Zhang², Y.M. Niquet³, C. Delerue², C. Tavernier¹ and H. Jaouen¹

¹STMicroelectronics, France, ²ISEN, France and ³CEA-UJF, France

15:00 **Coffee Break**

Session 4: Memory and Spin (Ginga)

Chairpersons: T. Kurusu, *Toshiba, Japan*

M. Stettler, *Intel, USA*

15:20

4-1 KNACK: A Hybrid Spin-Charge Mixed-Mode Simulator for Evaluating Different Genres of Spin-Transfer Torque MRAM Bit-cells

X. Fong, S. K. Gupta, N. N. Mojumder, S. H. Choday, C. Augustine and K. Roy

Purdue Univ., USA

15:40

4-2 Study of Current Induced Magnetic Domain Wall Movement with Extremely Low Energy Consumption by Micromagnetic Simulation

K. Kawabata, M. Tanizawa, K. Ishikawa, Y. Inoue, M. Inuishi and T. Nishimura

Renesas Electronics Corp., Japan

16:00

4-3 Properties of InAs- and Silicon-Based Ballistic Spin Field-Effect Transistors

D. Osintsev, V. Sverdlov, A. Makarov and S. Selberherr

TU Wien, Austria

16:20

4-4 Coupling the Level Set Method with an electro-thermal solver to simulate GST based PCM cells

A. Glière, O. Cueto and J. Hazart

CEA, LETI, France

16:40

4-5 Quantum Electronic Trap-to-Band Transitions in Chalcogenides Induced by Electron-Electron Interaction

F. Buscemi¹, E. Piccinini¹, F. Giovanardi¹, M. Rudan¹, R. Brunetti² and C. Jacoboni²

¹*Univ. Bologna, Italy* and ²*Univ. Modena and Reggio Emilia, Italy*

Session 5: Transport (Izumi)

Chairpersons: M. Ogawa, *Kobe Univ., Japan*

M. Rudan, *Univ. Bologna, Italy*

15:20

5-1 Tight-binding Study of Γ -L Bandstructure Engineering for Ballistic III-V nMOSFETs

Z. Yuan, A. Nainani, X. Guan, H. -S. P. Wong and K. C. Saraswat

Stanford Univ., USA

15:40

5-2 A Wigner Function-Based Determinist Method for the Simulation of Quantum Transport in Silicon Nanowire Transistors

S. Barraud, T. Poiroux and O. Faynot

CEA-Leti, France

16:00

5-3 Wigner Monte Carlo Approach to Quantum and Dissipative Transport in Si-MOSFETs

S. Koba, H. Tsuchiya and M. Ogawa

Kobe Univ., Japan

16:20

5-4 Impact of Channel Shape on Carrier Transport Investigated by Ensemble Monte Carlo/Molecular Dynamics Simulation

T. Kamioka^{1,4}, H. Imai^{1,4}, T. Watanabe^{1,4}, K. Ohmori^{2,4}, K. Shiraishi^{2,4} and Y. Kamakura^{3,4}
¹Waseda Univ., Japan, ²Tsukuba Univ., Japan, ³Osaka Univ., Japan and ⁴JST-CREST, Japan

16:40

5-5 Large-Signal Full-Band Monte Carlo Device Simulation of Millimeter-Wave Power GaN HEMTs with the Inclusion of Parasitic and Reliability Issues

D. Guerra¹, D. K. Ferry¹, S. M. Goodnick¹, M. Saraniti¹ and F. A. Marino²
¹Arizona State Univ., USA and ²Univ. Padova, Italy

17:00

5-6 Efficient Simulation of Quantum Cascade Lasers using the Pauli Master Equation

O. Baumgartner, Z. Stanojević and H. Kosina
TU Wien, Austria

18:00 **Reception**

Friday, September 9

Session 6: TCAD (Ginga)

Chairpersons: S. Yamakawa, *Sony Corp., Japan*

J. Lorentz, *Fraunhofer IISB, Germany*

9:00

6-1 (Invited) The Non-Equilibrium Green Function approach as a TCAD tool for future CMOS technology

A. Martinez¹, N. Seoane², M. Aldegunde³, A. Asenov⁴ and J.-R. Barker⁴
¹Univ. Swansea, UK, ²Univ. Santiago de Compostela, Spain, ³CESGA, Spain and ⁴Univ. Glasgow, UK

9:30

6-2 Exploring MOL Design Options for a 20nm CMOS Technology using TCAD

A. Scholze, S. Furkay, S-D. Kim and S. Jain

IBM SRDC, USA

9:50

6-3 Impact of Substrate Bias on GIDL for Thin-BOX ETSOI Devices

P. Kulkarni¹, Q. Liu², A. Khakifirooz¹, Y. Zhang¹, K. Cheng¹, F. Monsieur² and P. Oldiges¹

¹*IBM, USA and* ²*STMicroelectronics, USA*

10:10 **Coffee Break**

10:30

6-4 Impact of Quantum Confinement on Stress induced nMOSFET Threshold Voltage Shift

H. Takashino, M. Tanizawa, T. Okagaki, T. Hayashi, M. Taya, H. Ishida, K. Ishikawa and Y. Inoue

Renesas Electronics Corp., Japan

10:50

6-5 Thermoelectromechanical Simulation of GaN HEMTs

M.G. Ancona and S.C. Binari

Naval Research Lab., USA

11:10

6-6 Development of SF₆/O₂/Si Plasma Etching Topography Simulation Model using New Flux Estimation Method

T. Ikeda¹, H. Saito¹, F. Kawai¹, K. Hamada¹, T. Ohmine², H. Takada² and V. Deshpande³

¹*Toyota Motor Corp., Japan,* ²*Nihon Synopsys G.K., Japan and* ³*Synopsys Switzerland LLC, Switzerland*

11:30 **Lunch**

Session 7: Reliability II (Ginga)

Chairpersons: K. Sonoda, *Renesas Electronics, Japan*

C. Mouli, *Micron Semiconductor, USA*

13:00

7-1 (Invited) Density Functional Theory Based Simulation of Carrier Transport in Silicon

Carbide and Silicon Carbide-Silicon Dioxide Interfaces

A. Akturk¹, S. Salemi¹, N. Goldsman¹, S. Potbhare¹ and A. Lelis²

¹Univ. Maryland, USA and ²Army Research Lab., USA

13:30

7-2 Secondary generated holes as a crucial component for modeling of HC degradation in high-voltage n-MOSFET

S. Tyaginov¹, I. Starkov¹, O. Triebel¹, H. Ceric¹, T. Grasser¹, H. Enichlmair², J.M. Park² and C. Jungemann³

¹TU Wien, Austria, ²Austriamicrosystems AG, Austria and ³RWTH Aachen, Germany

13:50

7-3 Analysis of Worst-Case Hot-Carrier Degradation Conditions in the Case of n- and p-channel High-Voltage MOSFETs

I. Starkov¹, H. Ceric¹, S. Tyaginov¹, T. Grasser¹, H. Enichlmair², J.M. Park² and C. Jungemann³

¹TU Wien, Austria, ²Austriamicrosystems AG, Austria and ³RWTH Aachen, Germany

14:10

7-4 Reliability of NAND Flash Memories Induced by Anode Hole Generation in Floating-Gate

Y. Kitahara, D. Hagishima and K. Matsuzawa

Toshiba Corp., Japan

14:30

7-5 Multilevel Simulation for the Investigation of Fast Diffusivity Paths

H. Ceric, R. L. de Orio, F. Schanovsky, W. H. Zisser and S. Selberherr

TU Wien, Austria

15:00-17:00

Poster Session (Izumi)

Chairperson: S. Amakawa, *Hiroshima Univ., Japan*

P1 High-Quality Mesh Generation Based on Orthogonal Software Modules

J. Weinbub, J. Cervenka, K. Rupp and S. Selberherr

TU Wien, Austria

- P2 A Versatile Finite Volume Simulator for the Analysis of Electronic Properties of Nanostructures**
Z. Stanojević¹, M. Karner², K. Schnass², C. Kernstock², O. Baumgartner¹ and H. Kosina¹
¹TU Wien, Austria and ²Global TCAD Solutions, Austria
- P3 Parallel Preconditioning for Spherical Harmonics Expansions of the Boltzmann Transport Equation**
K. Rupp, T. Grasser and A. Jüngel
TU Wien, Austria
- P4 Adaptive Variable-Order Spherical Harmonics Expansion of the Boltzmann Transport Equation**
K. Rupp, T. Grasser and A. Jüngel
TU Wien, Austria
- P5 Inverse Modeling of sub-100nm MOSFET with PDE-Constrained Optimization**
C. Shen and D. Gong
Cogenda Pte Ltd., Singapore
- P6 A Smart Approach for Process Variation Correlation Modeling**
C-K. Lin, C. Hsiao, W-M. Chan and M-C. Jeng
Taiwan Semiconductor Manufacturing Co., Taiwan
- P7 A Parameterized SPICE Macromodel of Resistive Random Access Memory and Circuit Demonstration**
H-L. Chang¹, H-C. Li¹, C. W. Liu¹, F. Chen² and M.-J. Tsai²
¹National Taiwan Univ., Taiwan, R.O.C and ²Industrial Technology Research Instit., Taiwan, R.O.C.
- P8 The Flexible Compact SOI-MOSFET Model HiSIM-SOI Valid for Any Structural Types**
M. Miyake¹, S. Kusu¹, H. Kikuchihara¹, A. Tanaka¹, Y. Shintaku¹, M. Ueno¹,
J. Nakashima¹, U. Feldmann¹, H. J. Mattausch¹, M. Miura-Mattausch¹ and T. Yoshida²
¹Hiroshima Univ., Japan and ²NEC Informatec Systems, Ltd., Japan

- P9 Modeling of Enhanced 1/f Noise in TFT with Trap Charges**
T. Nakahagi¹, D. Sugiyama¹, S. Yukuta¹, M. Miyake¹, M. Miura-Mattausch¹ and S. Miyano²
¹Hiroshima Univ., Japan and ²NEC Energy Device, Ltd., Japan
- P10 Physical Circuit-Device Simulation of ESD and Power Devices**
V. Axelrad¹, H. Hayashi² and I. Kurachi³
¹SEQUOIA Design Systems Inc., USA, ²OKI Semiconductor Co. Ltd., Japan and ³Powerchip Technology Corp., Taiwan
- P11 A Novel Simulation Methodology for Development of ESD Primitives on a 0.18 μ m Analog, Mixed-Signal High Voltage Process Technology**
F. Roger, J. Cambieri and R. Minixhofer
Austriamicrosystems, Austria
- P12 TCAD simulations of irradiated power diodes over a wide temperature range**
M. Bellini¹ and J. Vobecký²
¹ABB CHCRC, Switzerland and ²ABB Semiconductors Ltd, Switzerland
- P13 3D TCAD Simulation of Advanced CMOS Image Sensors**
Z. Essa^{1,2}, P. Boulenc¹, C. Tavernier¹, F. Hirigoyen¹, A. Crocherie¹ and J. Michelot¹
¹STMicroelectronics, France and ²PHELMA Grenoble INP, France
- P14 a-Si/c-Si_{1-x}Ge_x/c-Si Heterojunction Solar Cells**
S. A. Hadi¹, A. Nayfeh¹, P. Hashemi² and J. Hoyt²
¹Masdar Inst. Science and Technol., UAE and ²MIT, USA
- P15 Impact of Energetic Disorder and Localization on the Conductivity and Mobility of Organic Semiconductors**
F. Torricelli¹, L. Colalongo², L. Milani², Z. M. K.-Vajna² and E. Cantatore¹
¹Eindhoven Univ. of Technol., Netherlands and ²Brescia Univ., Italy
- P16 Effect of the trap density and distribution of the silicon nitride layer on the retention characteristics of charge trap flash memory devices**
J. H. You¹, H. W. Kim¹, D. H. Kim¹, T. W. Kim¹ and K. W. Lee²
¹Hanyang Univ., Korea and ²Hynix Semiconductor Inc., Korea

- P17** **Enhancement of the device characteristics for nanoscale charge trap flash memory devices utilizing a metal spacer layer**
H. W. Kim¹, J. H. You¹, D. U. Lee¹, T. W. Kim¹ and K. W. Lee²
¹Hanyang Univ., Korea and ²Hynix Semiconductor Inc., Korea
- P18** **An Abnormal Floating Gate Interference and a Low Program Performance in 2y nm NAND Flash Devices**
E. Kwon, D. Oh, B. Lee, J-H. Yi, S. Kim, G. Cho, S. Park and J. Choi
Hynix Semiconductor Inc., Korea
- P19** **First Principles Study of the Switching Mechanism in Resistance Random Access Memory Devices**
H. Kasai¹, S. M. Aspera¹, H. Kishi¹, N. Awaya², S. Ohnishi² and Y. Tamai²
¹Osaka Univ., Japan and ²Sharp Corp., Japan
- P20** **First Principle Study of the Stability of H Atoms in SiN Layers on MONOS-Type Memories During Program/Erase Operations**
K. Yamaguchi¹, A. Otake¹, K. Kamiya¹, K. Shiraishi¹ and Y. Shigeta²
¹Tsukuba Univ., Japan and ²Osaka Univ., Japan
- P21** **Study on Carrier Mobility in Graphene Nanoribbons**
X. Yu¹, J. Zhang¹, J. Kang¹, H. Qian¹, Z. Yu¹ and Y. Tan²
¹Tsinghua Univ., China and ²Purdue Univ., USA
- P22** (withdrawn)
- P23** **Nanostructuring of Graphene Nanoribbons for thermoelectric applications**
F. Mazzamuto, J. S-Martin, V. H. Nguyen, Y. Apertet and P. Dollfus
Paris-Sud Univ., France.
- P24** **Analysis of geometrical structure and transport property in InAs/Si heterojunction nanowire tunneling field effect transistors**
Y. Miyoshi¹, M. Ogawa¹, S. Souma¹ and H. Nakamura²
¹Kobe Univ., Japan and ²IBM-Japan, Japan

P25 Simulation of Plasma Immersion Ion Implantation

A. Burenkov¹, P. Pichler¹, J. Lorenz¹, Y. Spiegel², J. Duchaine² and F. Torregrosa²
¹Fraunhofer IISB, Germany and ²Ion Beam Services, France

P26 Sticking coefficient of hydrogen radicals on ArF photoresist estimated by parallel plate structure in conjunction with numerical analysis

A. Malinowski^{1,2,3}, M. Sekine¹, M. Hori¹, K. Ishikawa¹, H. Kondo¹, T. Suzuki¹,
T. Takeuchi¹, H. Yamamoto¹, A. Jakubowski², L. Lukasiak² and D. Tomaszewski³
¹Nagoya Univ., Japan, ²Warsaw Univ. of Technol., Poland and ³Inst. Electron Technol.,
Poland

Saturday, September 10

Session 8: Compact Model (Ginga)

Chairpersons: T. Tanaka, *Fujitsu Semiconductor, Japan*
A. Heringa, *NXP Semiconductors, Netherland*

9:20

8-1 (Invited) A Spice-based Multi-physics Simulation Technique for Integrated MEMS

H. Toshiyoshi
Univ. Tokyo, Japan

9:50 **Coffee Break**

10:10

8-2 2D Analytical Model for the Study of NEM Relay Device Scaling

X. Shen, S. Chong, D. Lee, R. Parsa, R. T. Howe and H.-S. P. Wong
Stanford Univ., USA

10:30

8-3 Accurate and global model of SOI H gate body-tied MOSFET for circuit simulator

M. Mochizuki¹, H. Hayashi¹, S. Ishii¹, S. Ohira¹, I. Kurachi¹ and N. Miura²
¹Oki Semiconductor Co., Ltd., Japan and ²Oki Semiconductor Miyagi Co., Ltd., Japan

10:50

8-4 Modeling Temperature and Bias Stress Effect on Threshold Voltage of a-Si:H TFTs for Gate Driver Circuit Simulation

C.-H. Shen, Y. Li, I.-H. Lo, P.-J. Lin and S.-C. Chung

National Chiao Tung Univ., Taiwan

11:10

8-5 Characterization and Modeling of Self-Heating Effect on Transient Current Overshoot in Poly-Si TFTs Fabricated on Glass Substrate

T. Ota¹, H. Tsuji^{1,2}, Y. Kamakura¹ and K. Taniguchi¹

¹*Osaka Univ., Japan and* ²*CREST, Japan*

Session 9: Tunneling (Izumi)

Chairpersons: K. Fukuda, *AIST, Japan*

T. Grasser, *TU Wien, Austria*

10:10

9-1 3D Modeling based on Current Continuity for STM Carrier Profiling of Semiconductor Devices

K. Fukuda¹, M. Nishizawa¹, T. Tada¹, L. Bolotov², K. Suzuki³, S. Sato³, H. Arimoto¹ and T. Kanayama¹

¹*NIRC AIST, Japan,* ²*Tsukuba Univ., Japan and* ³*Fujitsu Semiconductor Ltd., Japan*

10:30

9-2 Analysis of Si, InAs, and Si-InAs Tunnel Diodes and Tunnel FETs Using Different Transport Models

A. Schenk¹, R. Rhyner¹, M. Luisier² and C. Bessire³

¹*ETH Zürich, Switzerland,* ²*Purdue Univ., USA and* ³*IBM Research-Zurich, Switzerland*

10:50

9-3 Analytical Approximation of Complex Band Structures for Band-to-Band Tunneling Models

X. Guan, D. Kim, K. C. Saraswat and H.-S. P. Wong

Stanford Univ., USA

11:10

9-4 Field Induced Quantum Confinement in Indirect Semiconductors: Quantum Mechanical and Modified Semiclassical Model

W. G. Vandenberghe^{1,2}, B. Sorée^{1,2}, W. Magnus^{1,3}, G. Groeseneken^{1,2}, A. S. Verhulst¹ and M. V. Fischetti⁴

¹*imec, Belgium,* ²*Katholieke Univ. Leuven, Belgium,* ³*Univ. Antwerpen, Belgium and* ⁴*Univ. Texas Dallas, USA*

11:30 **Lunch**

Session 10: Fluctuation (Ginga)

Chairpersons: Y. Li, *National Chiao Tung Univ., Taiwan*
A. Martinez, *Univ. Glasgow, UK*

13:00

10-1 Statistical MOSFET Current Variation Due to Variation in Surface Roughness Scattering

C.L. Alexander¹ and Asen Asenov^{1,2}

¹*Univ. Glasgow, UK and* ²*Gold Standard Simulations Ltd., UK*

13:20

10-2 A Mobility Model Correction for ‘Atomistic’ Drift-Diffusion Simulation

S. M. Amoroso¹, C. L. Alexander², S. Markov², G. Roy³ and A. Asenov^{2,3}

¹*Politecnico di Milano-IU.NET, Italy,* ²*Univ. Glasgow, UK and* ³*Gold Standard Simulations Ltd., UK*

13:40

10-3 The Effect of Compact Modelling Strategy on SNM and Read Current variability in Modern SRAM

P. Asenov¹, F. A. -Lema¹, S. Roy¹, C. Millar^{1,2}, A. Asenov^{1,2}, G. Roy², U. Kovac² and D. Reid²

¹*Univ. Glasgow, UK and* ²*Gold Standard Simulations Ltd., UK*

14:00

10-4 Nanosized Metal Grains Induced Electrical Characteristic Fluctuation in 16 nm Bulk and SOI FinFET Devices with TiN/HfO₂ Gate Stack

H.-W. Cheng, Y. Li, C.-Y. Yiu and H.-W. Su

National Chiao Tung Univ., Taiwan

14:20

10-5 Correlation between Interface Traps and Random Dopants in Emerging MOSFETs

Y.-Y. Chiu, Y. Li and H.-W. Cheng

National Chiao Tung Univ., Taiwan

14:40

**10-6 Schottky-barrier change by structural disorders at metal/Si interfaces:
First-principles study**

K. Kobinata and T. Nakayama

Chiba Univ., Japan

Session 11: Numerical Simulation Method (Izumi)

Chairpersons: T. Iwasaki, *Hitachi Ltd., Japan*

P. Oldiges, *IBM, USA*

13:00

**11-1 A Wavelet Method to Solve High-dimensional Transport Equations in Semiconductor
Devices**

V. Peikert and A. Schenk

ETH Zürich, Switzerland

13:20

**11-2 Numerical Methods for A Quantum Energy Transport Model Arising in Scaled
MOSFETs**

S. Sho and S. Odanaka

Osaka Univ., Japan

13:40

**11-3 A Level Set Simulator for Nanooxidation using Non-Contact Atomic Force
Microscopy**

L. Filipovic and S. Selberherr

TU Wien, Austria

14:00

**11-4 Bridge-Function Pseudospectral Method for Quantum Mechanical Simulation of
Nano-Scaled Devices**

Y. Saitou, T. Nakamori, S. Souma and M. Ogawa

Kobe Univ., Japan

14:20

11-5 Low-dimensional Quantum Transport Models in Atomistic Device Simulations

G. Mil'nikov^{1,2}, N. Mori^{1,2} and Y. Kamakura^{1,2}

¹*Osaka Univ., Japan and* ²*CREST, JST, Japan*